HOSTAFORM® C 9021 TF XAP®2

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Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988- POM-K, M-GNS, 2-2 POM copolymer Injection molding type, modified with PTFE; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation; for sliding combinations with very low coefficient of friction. Reduced emission grade. Emissions according to VDA 275 < 5 mg/kg Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1 mm. Ranges of applications: For sliding combinations with very low coefficient of friction. FMVSS = Federal Motor Vehicle Safety Standard (USA)

Product information

Resin Identification	POM+PTFE	ISO 1043
Part Marking Code	>POM+PTFE<	ISO 11469

Rheological properties

Melt volume-flow rate	6	$cm^3/10min$	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	2.0	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.7	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	2350	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	50	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	10	%	ISO 527-1/-2
Nominal strain at break	16	%	ISO 527-1/-2
Flexural modulus	2250	MPa	ISO 178
Tensile creep modulus, 1h	2000	MPa	ISO 899-1
Tensile creep modulus, 1000h	1150	MPa	ISO 899-1
Charpy impact strength, 23°C	60	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	60	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	4	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	4	kJ/m^2	ISO 179/1eA
Ball indentation hardness, H 358/30	120	MPa	ISO 2039-1
Poisson's ratio	0.38[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	98	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	110	E-6/K	ISO 11359-1/-2

Flammability

Burning rate, Thickness 1 mm	72.6	mm/min	ISO 3795 (FMVSS 302)

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Electrical properties

Relative permittivity, 100Hz	3.7		IEC 62631-2-1
Relative permittivity, 1MHz	3.7		IEC 62631-2-1
Dissipation factor, 100Hz	20	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	80	E-4	IEC 62631-2-1
Volume resistivity	1E12	Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	Ohm	IEC 62631-3-2
Electric strength	33	kV/mm	IEC 60243-1
Comparative tracking index	600		IEC 60112

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	1510	kg/m³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa

Characteristics

Processing	Injection Moulding, Other Extrusion
Delivery form	Pellets
Additives	Release agent
Special characteristics	Low wear / Low friction, Low emissions

Additional information

Processing Notes

Pre-Drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose.

Storage

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The product can then be stored in standard conditions until processed.

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Mercedes-Benz	DBL5404	BQF
Mercedes-Benz	DBL5410	

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